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## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



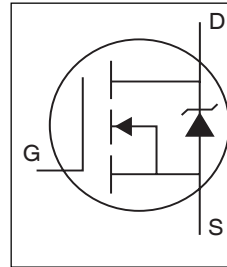
# IRLR8503PbF

- N-Channel Application-Specific MOSFET
- Ideal for CPU Core DC-DC Converters
- Low Conduction Losses
- Minimizes Parallel MOSFETs for high current applications
- Lead-Free

## HEXFET® MOSFET for DC-DC Converters

### Description

This new device employs advanced HEXFET Power MOSFET technology to achieve very low on-resistance. The reduced conduction losses makes it ideal for high efficiency DC-DC converters that power the latest generation of microprocessors.



The IRLR8503 has been optimized and is 100% tested for all parameters that are critical in synchronous buck converters including  $R_{DS(on)}$ , gate charge and  $C_{dv/dt}$ -induced turn-on immunity. The IRLR8503 offers an extremely low combination of  $Q_{sw}$  &  $R_{DS(on)}$  for reduced losses in control FET applications.

### DEVICE RATINGS (MAX. Values)

IRLR8503PbF	
$V_{DS}$	30V
$R_{DS(on)}$	18 mΩ
$Q_G$	20 nC
$Q_{sw}$	8 nC
$Q_{oss}$	29.5 nC

The package is designed for vapor phase, infra-red, convection, or wave soldering techniques. Power dissipation of greater than 2W is possible in a typical PCB mount application.

### Absolute Maximum Ratings

Parameter	Symbol	IRLR8503	Units
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	±20	
Continuous Drain or Source Current ( $V_{GS} \geq 10V$ ) <sup>⑤</sup>	$T_C = 25^\circ C$	$I_D$	A
	$T_C = 90^\circ C$		
Pulsed Drain Current <sup>①</sup>	$I_{DM}$	196	
Power Dissipation <sup>⑤</sup>	$T_C = 25^\circ C$	$P_D$	W
	$T_C = 90^\circ C$		
Junction & Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C
Continuous Source Current (Body Diode)	$I_S$	15	A
Pulsed source Current <sup>①</sup>	$I_{SM}$	196	

### Thermal Resistance

Parameter	Symbol	Max.	Units
Maximum Junction-to-Ambient <sup>③</sup>	$R_{\theta JA}$	50	°C/W
Maximum Junction-to-Lead	$R_{\theta JL}$	2.0	°C/W

## Electrical Characteristics

Parameter	Symbol	Min	Typ	Max	Units	Conditions
Drain-to-Source Breakdown Voltage*	$V_{(BR)DSS}$	30	–	–	V	$V_{GS} = 0V, I_D = 250\mu A$
Static Drain-Source on Resistance*	$R_{DS(on)}$	–	11	16	m $\Omega$	$V_{GS} = 10V, I_D = 15A$ ⓐ
		–	13	18		$V_{GS} = 4.5V, I_D = 15A$
Gate Threshold Voltage*	$V_{GS(th)}$	1.0			V	$V_{DS} = V_{GS}, I_D = 250\mu A$
Drain-Source Leakage Current	$I_{DSS}$	–	–	30*	$\mu A$	$V_{DS} = 24V, V_{GS} = 0$
		–	–	150		$V_{DS} = 24V, V_{GS} = 0,$ $T_J = 100^\circ C$
Gate-Source Leakage Current*	$I_{GSS}$	–	–	$\pm 100$	nA	$V_{GS} = \pm 12V$
Total Gate Charge Control FET*	$Q_g$	–	15	20	nC	$V_{GS} = 5V, I_D = 15A, V_{DS} = 16V,$
Total Gate Charge Sync FET*	$Q_g$	–	13	17		$V_{GS} = 5V, V_{DS} < 100mV$
Pre-Vth Gate-Source Charge	$Q_{gs1}$	–	3.7	–		$V_{DS} = 16V, I_D = 15A$
Post-Vth Gate-Source Charge	$Q_{gs2}$	–	1.3	–		
Gate to Drain Charge	$Q_{gd}$	–	4.1	–		
Switch Charge* ( $Q_{gs2} + Q_{gd}$ )	$Q_{SW}$	–	5.4	8		
Output Charge*	$Q_{OSS}$	–	23	29.5		$V_{DS} = 16V, V_{GS} = 0$
Gate Resistance	$R_g$	–	1.7	–	$\Omega$	
Turn-on Delay Time	$t_{d(on)}$	–	10	–	ns	$V_{DD} = 16V, I_D = 15A$
Drain Voltage Rise Time	$t_{rv}$	–	18	–		$V_{GS} = 5V$
Turn-off Delay Time	$t_{d(off)}$	–	11	–		Clamped Inductive Load
Drain Voltage Fall Time	$t_{fv}$	–	3	–		See test diagram Fig 14.
Input Capacitance	$C_{iss}$	–	1650	–	pF	$V_{DS} = 25V, V_{GS} = 0$
Output Capacitance	$C_{oss}$	–	650	–		
Reverse Transfer Capacitance	$C_{rss}$	–	58	–		

## Source-Drain Rating & Characteristics

Parameter	Symbol	Min	Typ	Max	Units	Conditions
Diode Forward Voltage*	$V_{SD}$	–		1.0	V	$I_S = 15A$ ⓐ, $V_{GS} = 0V$
Reverse Recovery Charge <sup>④</sup>	$Q_{rr}$	–	76		nC	$di/dt = 700A/\mu s$ $V_{DS} = 16V, V_{GS} = 0V, I_S = 15A$
Reverse Recovery Charge (with Parallel Schottky) <sup>④</sup>	$Q_{rr(s)}$	–	67			$di/dt = 700A/\mu s$ (with 10BQ040) $V_{DS} = 16V, V_{GS} = 0V, I_S = 15A$

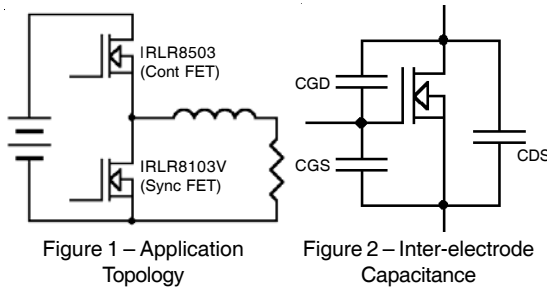
### Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Pulse width  $\leq 300 \mu s$ ; duty cycle  $\leq 2\%$ .
- ③ When mounted on 1 inch square copper board,  $t < 10$  sec.
- ④ Typ = measured -  $Q_{oss}$
- ⑤ Calculated continuous current based on maximum allowable Junction temperature; switching and other losses will decrease RMS current capability; package limitation current = 20A.

\* Devices are 100% tested to these parameters.



**Power MOSFET Optimization for DC-DC Converters**  
While the IRLR8103V and IRLR8503 can and are being used in a variety of applications, they were designed and optimized for low voltage DC-DC conversion in a synchronous buck converter topology, specifically, microprocessor power applications. The IRLR8503 (Figure 1) was optimized for the control FET socket, while the IRLR8103V was optimized for the synchronous FET function.



Because of the inter-electrode capacitance (Figure 2) of the Power MOSFET, specifying the  $R_{\text{DS(on)}}$  of the device is not enough to ensure good performance. An optimization between  $R_{\text{DS(on)}}$  and charge must be performed to insure the best performing MOSFET for a given application. Both die size and device architecture must be varied to achieve the minimum possible in-circuit losses. This is independently true for both control FET and synchronous FET. Unfortunately, the capacitances of a FET are non-linear and voltage dependent. Therefore, it is inconvenient to specify and use them effectively in switching power supply power loss estimations. This was well understood years ago and resulted in changing the emphasis from capacitance to gate charge on Power MOSFET data sheets.

Table 1 – Traditional Charge Parameters

Device Capacitance	Corresponding Charge Parameter
$C_{\text{GS}}$	$Q_{\text{GS}}$
$C_{\text{GS}} + C_{\text{GD}}$	$Q_{\text{G}}$
$C_{\text{GD}}$	$Q_{\text{GD}}$

International Rectifier has recently taken the industry a step further by specifying new charge parameters that are even more specific to DC-DC converter design (Table 2). In order to understand these parameters, it is best to start with the in-circuit waveforms in Figure 3 & Figure 4.

Table 2 – New Charge Parameters

New Charge Parameter	Description	Waveform
$Q_{\text{GS1}}$	Pre-Threshold Gate Charge	Figure 3
$Q_{\text{GS2}}$	Post-Threshold Gate Charge	
$Q_{\text{GCONT}}$	Control FET Total $Q_{\text{G}}$	
$Q_{\text{SWITCH}}$	Charge during control FET switching Combines $Q_{\text{GS2}}$ and $Q_{\text{GD}}$	Figure 5 Figure 6
$Q_{\text{OSS}}$	Output charge Charge supplied to $C_{\text{OSS}}$ during the $Q_{\text{GD}}$ period of control FET switching	
$Q_{\text{GSYNC}}$	Synchronous FET Total $Q_{\text{G}}$ ( $V_{\text{DS}} \leq 0$ )	Figure 4

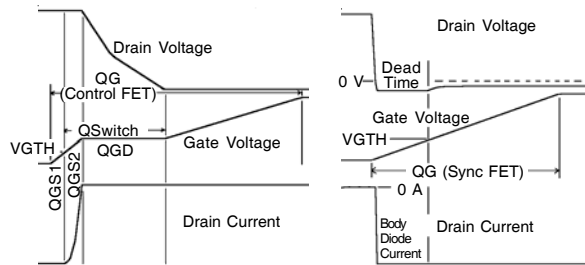


Figure 3 – Control FET Waveform

Figure 4 – Sync FET Waveform

The waveforms are broken into segments corresponding to charge parameters. These, in turn, correspond to discrete time segments of the switching waveform.

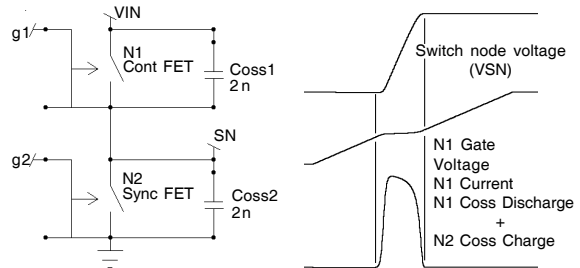


Figure 5 –  $Q_{\text{OSS}}$  Equivalent Circuit

Figure 6 –  $Q_{\text{OSS}}$  Waveforms

Losses may be broken into four categories: conduction loss, gate drive loss, switching loss, and output loss. The following simplified power loss equation is true for both MOSFETs in a synchronous buck converter:

$$P_{\text{LOSS}} = P_{\text{CONDUCTION}} + P_{\text{GATE DRIVE}} + P_{\text{SWITCH}} + P_{\text{OUTPUT}}$$

For the synchronous FET, the  $P_{\text{SWITCH}}$  term becomes virtually zero and is ignored.

# IRLR8503PbF



Table 3 and Table 4 describes the event during the various charge segments and shows an approximation of losses during that period.

Table 3 – Control FET Losses

	Description	Segment Losses
Conduction Loss	Losses associated with MOSFET on time. $I_{RMS}$ is a function of load current and duty cycle.	$P_{COND} = I_{RMS}^2 \times R_{DS(on)}$
Gate Drive Loss	Losses associated with charging and discharging the gate of the MOSFET every cycle. Use the control FET $Q_G$ .	$P_{IN} = V_G \times Q_G \times f$
Switching Loss	Losses during the drain voltage and drain current transitions for every full cycle. Losses occur during the $Q_{GS2}$ and $Q_{GD}$ time period and can be simplified by using $Q_{switch}$ .	$P_{QGS2} \approx V_{IN} \times I_L \times \frac{Q_{GS2}}{I_G} \times f$ $P_{QGD} \approx V_{IN} \times I_L \times \frac{Q_{GD}}{I_G} \times f$ $P_{SWITCH} \approx V_{IN} \times I_L \times \frac{Q_{SW}}{I_G} \times f$
Output Loss	Losses associated with the $Q_{OSS}$ of the device every cycle when the control FET turns on. Losses are caused by both FETs, but are dissipated by the control FET.	$P_{OUTPUT} = \frac{Q_{OSS}}{2} \times V_{IN} \times F$

Table 4 – Synchronous FET Losses

	Description	Segment Losses
Conduction Loss	Losses associated with MOSFET on time. $I_{RMS}$ is a function of load current and duty cycle.	$P_{COND} = I_{RMS}^2 \times R_{DS(on)}$
Gate Drive Loss	Losses associated with charging and discharging the gate of the MOSFET every cycle. Use the Sync FET $Q_G$ .	$P_{IN} = V_G \times Q_G \times f$
Switching Loss	Generally small enough to ignore except at light loads when the current reverses in the output inductor. Under these conditions various light load power saving techniques are employed by the control IC to maintain switching losses to a negligible level.	$P_{SWITCH} \approx 0$
Output Loss	Losses associated with the $Q_{OSS}$ of the device every cycle when the control FET turns on. They are caused by the synchronous FET, but are dissipated in the control FET.	$P_{OUTPUT} = \frac{Q_{OSS}}{2} \times V_{IN} \times f$

## Typical PC Application

The IRLR8103V and the IRLR8503 are suitable for Synchronous Buck DC-DC Converters, and are optimized for use in next generation CPU applications. The IRLR8103V is primarily optimized for use as the low side synchronous FET (Q2) with low  $R_{DS(on)}$  and high CdV/dt immunity. The IRLR8503 is primarily optimized for use as the high side control FET (Q1) with low combined  $Q_{sw}$  and  $R_{DS(on)}$ , but can also be used as a synchronous FET. The IRLR8503 is also tested for CdV/dt immunity, critical for the low side socket. The typical configuration in which these devices may be used in shown in Figure 7.

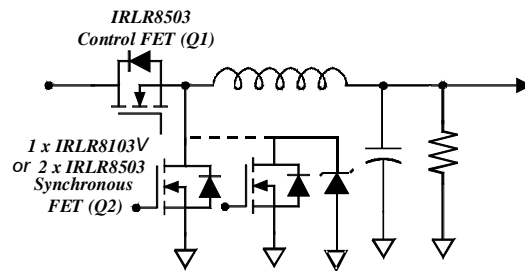


Figure 7. 2 & 3-FET solution for Synchronous Buck Topology.

**Typical Characteristics**  
**IRLR8503**

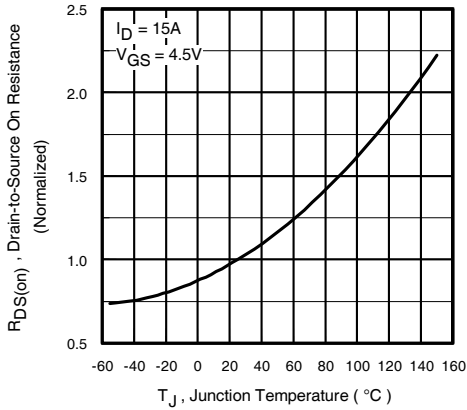


Figure 8. Normalized On-Resistance vs. Temperature

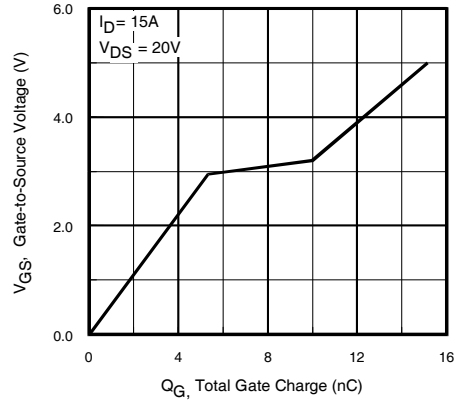


Figure 9. Gate-to-Source Voltage vs. Typical Gate Charge

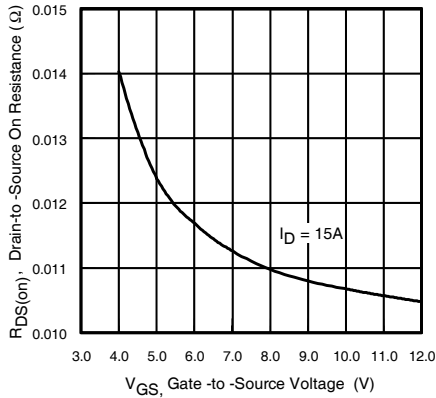


Figure 10. Typical  $R_{ds(on)}$  vs. Gate-to-Source Voltage

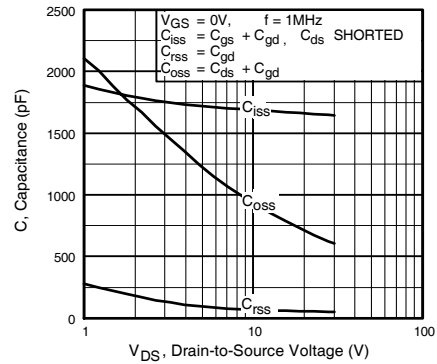


Figure 11. Typical Capacitance vs. Drain-to-Source Voltage

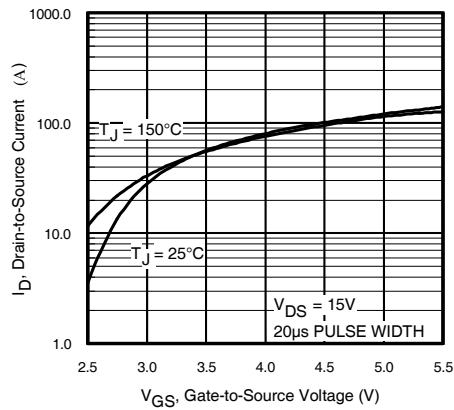
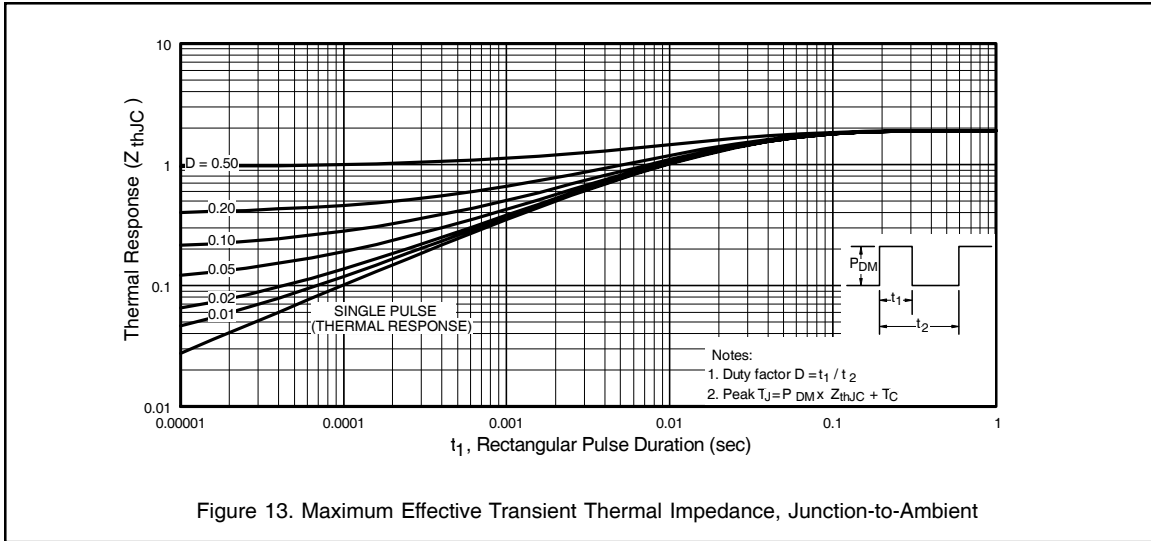


Figure 12. Typical Transfer Characteristics



## Inductive Load Circuit

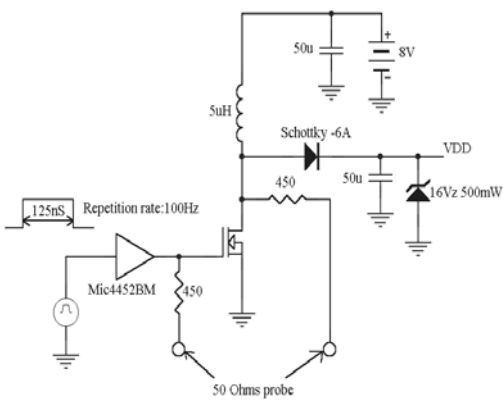
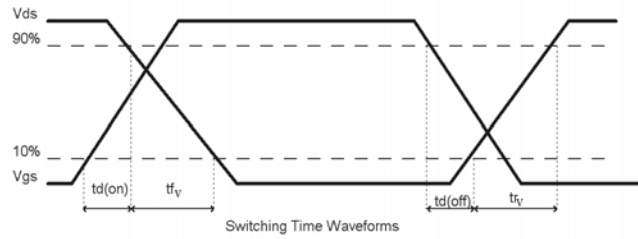
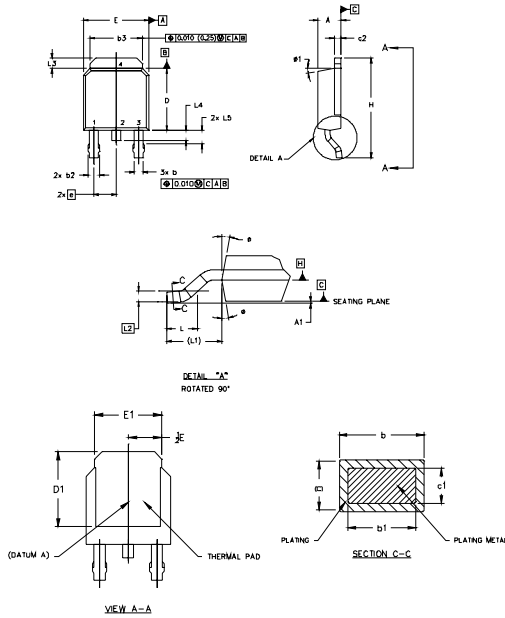


Figure 14. Clamped Inductive Load test diagram



## D-Pak (TO-252AA) Package Outline

Dimensions are shown in millimeters (inches)



NOTES:

- 1.0 DIMENSIONING AND TOLERANCING PER ASME Y14.5 M- 1994.
- 2.0 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS].
- 3.0 LEAD DIMENSION UNCONTROLLED IN L5.
- 4.0 DIMENSION D1 AND E1 ESTABLISH A MINIMUM MOUNTING SURFACE FOR THERMAL PAD.
- 5.0 SECTION C-C DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 [0.127] AND .010 [0.2540] FROM THE LEAD TIP.
- 6.0 DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- 7.0 OUTLINE CONFORMS TO JEDEC OUTLINE TO-252AA.

SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN	MAX	MIN	MAX	
A	2.18	2.29	.086	.094	
A1		0.13		.005	
b	0.84	0.96	.033	.038	
b1	0.84	0.79	.033	.032	
b2	0.76	1.14	.030	.045	
b3	4.92	5.46	.193	.215	
c	0.48	0.61	.018	.024	5
c1	0.41	0.56	.016	.022	5
c2	0.68	0.98	.028	.039	5
D	6.97	8.22	.275	.324	6
D1	6.21	-	.245	-	4
E	6.35	6.13	.250	.243	6
E1	4.32	-	.170	-	4
e	2.29		.090	BSC	
H	6.40	10.41	.250	.410	
L	1.60	1.78	.063	.070	
L1	2.74 REF.		.108 REF.		
L2	0.508 BSC		.020 BSC		
L3	1.08	1.27	.043	.050	
L4		1.02		.040	
L5	1.14	1.52	.045	.060	3
a	0°	10°	0°	10°	
#1	0°	10°	0°	15°	

LEAD ASSIGNMENTS

- 1- GATE
- 2- DRAIN
- 3- SOURCE
- 4- DRAIN

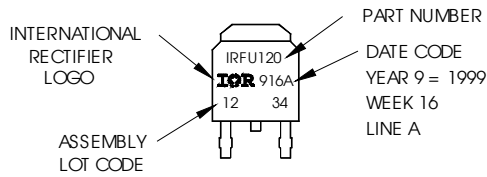
IGBTs, CuPACK

- 1- GATE
- 2- COLLECTOR
- 3- EMITTER
- 4- COLLECTOR

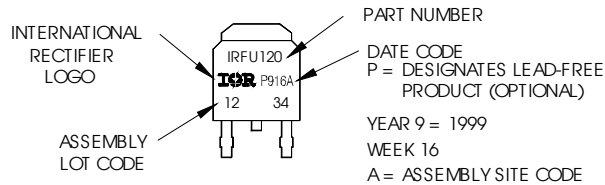
## D-Pak (TO-252AA) Part Marking Information

EXAMPLE: THIS IS AN IRFU120  
WITH ASSEMBLY  
LOT CODE 1234  
ASSEMBLED ON WW 16, 1999  
IN THE ASSEMBLY LINE "A"

Note: "P" in assembly line position  
indicates "Lead-Free"



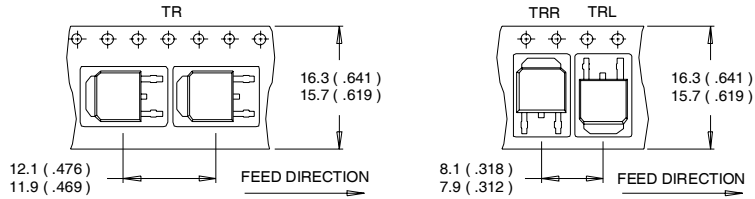
OR



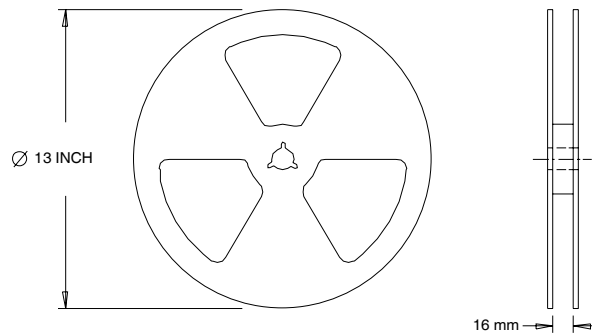


## D-Pak (TO-252AA) Tape & Reel Information

Dimensions are shown in millimeters (inches)



- NOTES :
1. CONTROLLING DIMENSION : MILLIMETER.
  2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS ( INCHES ).
  3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



- NOTES :
1. OUTLINE CONFORMS TO EIA-481.

Data and specifications subject to change without notice.  
 This product has been designed and qualified for the commercial market.  
 Qualification Standards can be found on IR's Web site.

Note: For the most current drawings please refer to the IR website at:  
<http://www.irf.com/package/>